



- A1/B1** EMS Electronic manufacturing services, PCBs and other circuit carriers
- A2** Electromechanics and system peripherals, Interconnection components
- A2** Electromechanics and system peripherals, Interconnection components, Relays, switches and keyboards
- B3** Electromechanics and system peripherals, Interconnection components, Casing technology
- C6** EMS Electronics manufacturing services, PCBs and other circuit carriers, Electromechanics and system peripherals
- A3** Test and measurement
- A4** Power supplies
- A5-6** Passive components
- B3** Sensor technology, Micro- and nanosystems (NEMS, MEMS)
- B4** **all halls** Embedded systems
- B4-5** **C3-5** Semiconductors
- B6** Displays
- B6** **all halls** Automotive
- B6** Wireless
- C1-2** SEMICON Europa 2024
- all halls** ED/EDA / Servo-technology / Assemblies and subsystems / Services
- ICM** **Conferences**
  - electronica Automotive Conference
  - Wireless Congress

- Forums**
  - A1: PCB, EMS & Components Marketplace**
    - PCB, EMS & Components
    - Printed Electronics by LOPEC & OE-A
  - A4: electronica Stage**
    - Electrical Connectors
    - Measurement Technology
  - A5: Power Efficiency Stage**
    - Embedded Systems
    - Power Electronics
  - B4: Start-up Stage**
    - electronica Fast Forward
  - B4: Visionary Stage**
    - Cyber Security
    - Industrial IoT: AI/Machine Learning, 5G & Edge Computing
    - Women in Tech
  - B6: Smart Mobility Stage**
    - Automotive
    - Printed Electronics by LOPEC & OE-A
  - C5: Future Control Stage**
    - Embedded Platforms
    - Industrial Control
  - SEMICON Europa Forums**
    - SEMICON Europa TechARENA (C1)
    - SEMICON Europa Executive Forum (C2)



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# Plan of the fair grounds

Planning status as of: 5/2024 (Subject to change)